



Transient Voltage Suppressors for ESD Protection

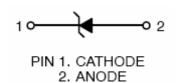
FEATURES:

- Ultra Low Capacitance 0.5 pF
- Low Clamping Voltage
- Small Body Outline Dimensions: 0.039" x 0.024" (1.00 mm x 0.60 mm)
- Low Body Height: 0.016" (0.4 mm)
- Stand-off Voltage: 5 V
- Low Leakage
- Response Time is Typically < 1.0 ns
- IEC61000-4-2 Level 4 ESD Protection
- This is a Pb-Free Device

Circuit Diagram & Pin Configuration:



SOD-923



DEVICE MARKING AND ORDERING INFORMATION

| Device | Marking | Shipping | |
|--------------|---------|----------------|--|
| TESDL051AD92 | D | 8000/Tape&Reel | |

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|------------------|-------------|------|
| IEC 61000-4-2 (ESD) Contact Air | | ±10 ±15 | kV |
| Total Power Dissipation on FR-5 Board (Note 1) @ T _A = 25°C | P _D | 150 | mW |
| Storage Temperature Range | T _{stg} | -55 to +150 | °C |
| Junction Temperature Range | TJ | -55 to +125 | °C |
| Lead Solder Temperature – Maximum (10 Second Duration) | TL | 260 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. $FR-5 = 1.0 \times 0.75 \times 0.62$ in.

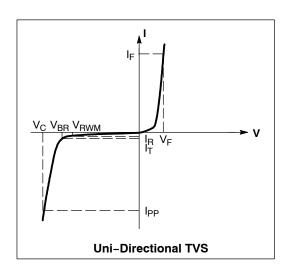


TESDL051AD92

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

| ` '' | , | | | | |
|-----------------|--|--|--|--|--|
| Symbol | Parameter | | | | |
| I _{PP} | Maximum Reverse Peak Pulse Current | | | | |
| V _C | Clamping Voltage @ I _{PP} | | | | |
| V_{RWM} | Working Peak Reverse Voltage | | | | |
| I _R | Maximum Reverse Leakage Current @ V _{RWM} | | | | |
| V_{BR} | Breakdown Voltage @ I _T | | | | |
| Ι _Τ | Test Current | | | | |
| I _F | Forward Current | | | | |
| V _F | Forward Voltage @ I _F | | | | |
| P _{pk} | Peak Power Dissipation | | | | |
| С | Capacitance @ V _R = 0 and f = 1.0 MHz | | | | |



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 1.0 \text{ V}$ Max. @ $I_F = 10 \text{ mA}$ for all types)

| | V _{RWM} (V) | I _R (μΑ) @ V _{RWM} | V _{BR} (V) @ I _T (Note 2) | l _T | С | (pF) | V _C (V) @ I _{PP} = 1 A (Note 3) | v _c |
|--------------|----------------------|---|--|----------------|-----|------|---|------------------------------|
| Device | Max | Max | Min | mA | Тур | Max | Max | Per IEC61000-4-2 (Note 4) |
| TESDL051AD92 | 5.0 | 1.0 | 5.4 | 1.0 | 0.5 | 0.9 | 9.8 | Figures 1 and 2 See Below |

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.
 Surge current waveform per Figure 5.
 For test procedure see Figures 3 and 4.



Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV Contact per IEC61000-4-2



Figure 2. ESD Clamping Voltage Screenshot Negative 8 kV Contact per IEC61000-4-2



IEC 61000-4-2 Spec.

| Level | Test Voltage (kV) | First Peak Current (A) | Current at 30 ns (A) | Current at 60 ns (A) |
|-------|-------------------------|------------------------------|-------------------------|-------------------------|
| 1 | 2 | 7.5 | 4 | 2 |
| 2 | 4 | 15 | 8 | 4 |
| 3 | 6 | 22.5 | 12 | 6 |
| 4 | 8 | 30 | 16 | 8 |

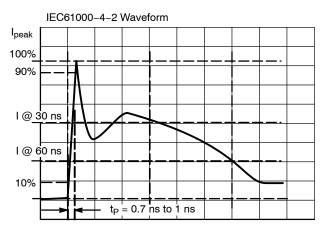


Figure 3. IEC61000-4-2 Spec

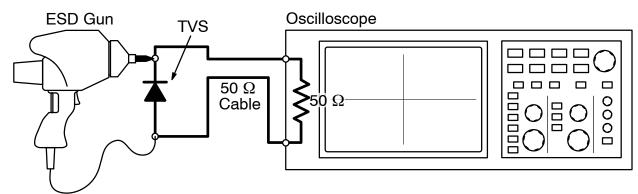


Figure 4. Diagram of ESD Test Setup

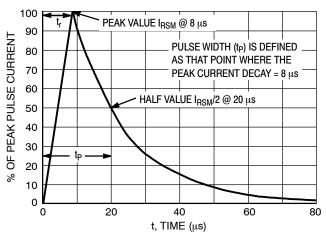
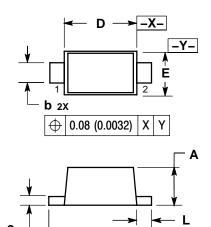


Figure 5. 8 X 20 μs Pulse Waveform



TESDL051AD92

SOD-923

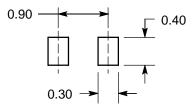


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| | MILLIMETERS | | | INCHES | | | |
|-----|-------------|------|------|--------|-------|-------|--|
| DIM | MIN | NOM | MAX | MIN | MON | MAX | |
| Α | 0.34 | 0.37 | 0.40 | 0.013 | 0.015 | 0.016 | |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 800.0 | 0.010 | |
| С | 0.07 | 0.12 | 0.17 | 0.003 | 0.005 | 0.007 | |
| D | 0.75 | 0.80 | 0.85 | 0.030 | 0.031 | 0.033 | |
| Ε | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 | |
| HE | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 | |
| L | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 | |

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTICE

The information presented in this document is for reference only. Tinysemi reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tintsemi elec Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

This publication supersedes & replaces all information reviously supplied. For additional information, please visit our website http://www.tinysemi.com, or consult your nearest Tinysemi's sales office for further assistance.